



Revision: 1.0
Date: 4-Mar-05

Statement of Materials, Construction

16L COB -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Substrate	BT Resin	0.01737	BT Epoxy	Proprietary	0.00434	15.02595	25
				Glass Crossing	Proprietary	0.00693	23.98142	39.9
				Cu	7440-50-8	0.00608	21.03633	35
				Ni	7440-02-0	0.00002	0.06010	0.1
2	Die	Silicon Chip	0.002010	Si	7440-21-3	0.00201	6.95502	100
3	Die attach material	84-1 LMISR4	0.000570	Epoxy resin (5-25)	Proprietary	0.00009	0.29585	15
				Silver (70-85)	7440-21-3	0.00046	1.57785	80
				Aromatic Amine (1-10)	Proprietary	0.00003	0.09862	5
4	Wire	Gold	0.0007480	Au	7440-57-5	0.00075	2.58798	99.99
5	Encapsulation NT-309HQ	Epoxy Resin	0.008202	Bisphenol A type	25068-38-6	0.00443	15.32554	54
				Epoxy resin	2451-62-9	0.00131	4.54090	16
				Tetra Hydrophthalic Anhydride	85-43-8	0.002461	8.51390	29.999
				Halogenated Flame Retardants	Proprietary	0.00000	0.00028	0.001
Total Package weight			0.0289					

Note: Composition derived from MSDS and material C of C from Vendors;
Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead*	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%